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Vishay Siliconix

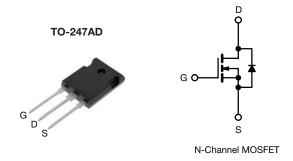
RoHS

COMPLIANT HALOGEN

FREE

EF Series Power MOSFET with Fast Body Diode

PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	650				
R _{DS(on)} typ. at 25 °C (Ω)	V _{GS} = 10 V 0.033				
Q _g (Max.) (nC)	380				
Q _{gs} (nC)	62				
Q _{gd} (nC)	102				
Configuration	Single				



FEATURES

- Fast body diode MOSFET using E series technology
- Reduced t_{rr}, Q_{rr}, and I_{RRM}
- Low figure-of-merit (FOM): Ron x Qg
- Low input capacitance (Ciss)
- Increased robustness due to low Q_{rr}
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Telecommunications
 - Server and telecom power supplies
- Lighting
 - High intensity discharge (HID)
 - Light emitting diodes (LEDs)
- Consumer and computing
 - ATX power supplies
- Industrial
 - Welding
 - Battery chargers
- Renewable energy
 - Solar (PV inverters)
- Switch mode power suppliers (SMPS)
- Applications using the following topologies
 - LLC
 - Phase shifted bridge (ZVS)
 - 3-level inverter
 - AC/DC bridge

ORDERING INFORMATION	
Package	TO-247AD
Lead (Pb)-free and Halogen-free	SiHW70N60EF-GE3

ABSOLUTE MAXIMUM RATINGS (TC	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V_{DS}	600	V
Gate-Source Voltage			V_{GS}	± 30	7 v
Continuous Drain Current /T 150 °C)	V _{GS} at 10 V	T _C = 25 °C	- I _D	70	
Continuous Drain Current (T _J = 150 °C)		T _C = 100 °C		45	Α
Pulsed Drain Current ^a			I _{DM}	229	
Linear Derating Factor				4.2	W/°C
Single Pulse Avalanche Energy b			E _{AS}	1706	mJ
Maximum Power Dissipation			P_{D}	520	W
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C
Drain-Source Voltage Slope T _J = 125 °C		dV/dt	70	1//	
Reverse Diode dV/dt ^d			50	- V/ns	
Soldering Recommendations (Peak Temperature) c	ng Recommendations (Peak Temperature) c for 10 s			300	°C

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 11 A
- c. 1.6 mm from case
- d. $I_{SD} = 35 \text{ A}$, $dI/dt = 750 \text{ A/}\mu\text{s}$, $V_{DS} = 400 \text{ V}$



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THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R _{thJA}	-	40	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.24	C/VV

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static				l		I.	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D = 250 μA	600	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.69	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Cata Sauraa Laakaga	1		V _{GS} = ± 20 V	-	-	± 100	nA
Gate-Source Leakage	I _{GSS}	V _{GS} = ± 30 V		-	-	± 1	μΑ
Zava Cata Valtaga Dvais Cuvvent		V _{DS} =	= 480 V, V _{GS} = 0 V	-	-	1	μΑ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 480 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	2	mA
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 \text{ V}$	$I_D = 35 A$	-	0.033	0.038	Ω
Forward Transconductance	9 _{fs}	V_{DS}	$= 30 \text{ V}, I_D = 35 \text{ A}$	-	25	-	S
Dynamic							
Input Capacitance	C _{iss}		$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$		7500	-	
Output Capacitance	Coss				378	-	
Reverse Transfer Capacitance	C_{rss}	f = 1 MHz		-	5	-	
Effective output capacitance, energy related ^a	$C_{o(er)}$., .,	/	-	263	-	pF
Effective output capacitance, time related ^b	C _{o(tr)}	V _{GS} = 0	/, V _{DS} = 0 V to 480 V	-	926	-	
Total Gate Charge	Qg			-	253	380	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$I_D = 35 A, V_{DS} = 480 V$	-	62	-	nC
Gate-Drain Charge	Q _{gd}			-	102	-	
Turn-On Delay Time	t _{d(on)}			-	56	84	
Rise Time	t _r	V _{DD} = 480 V, I _D = 35 A		-	107	161	no
Turn-Off Delay Time	t _{d(off)}	$R_g = 1$	9.1 Ω , $V_{GS} = 10 \text{ V}$	-	257	386	ns
Fall Time	t _f			-	123	185	
Gate Input Resistance	R_g	f = 1	MHz, open drain	0.5	1.1	2.2	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	70	
Pulsed Diode Forward Current	I _{SM}			-	-	229	- A
Diode Forward Voltage	V _{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 35 \text{A}, V_{GS} = 0 \text{V}$		-	0.9	1.2	V
Reverse Recovery Time	t _{rr}			-	213	426	ns
Reverse Recovery Charge	Q _{rr}		5 °C, I _F = I _S = 35 A, 100 A/µs, V _R = 400 V	-	1.6	3.2	μC
Reverse Recovery Current	I _{RRM}	ui/ul =	100 AV µS, VR = 400 V	_	16	-	Α

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

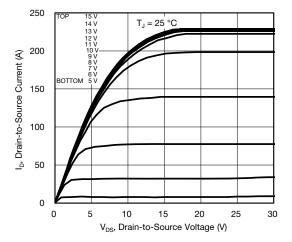


Fig. 1 - Typical Output Characteristics

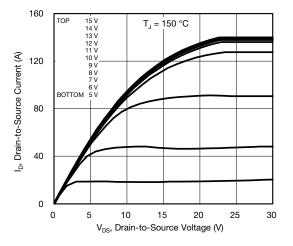


Fig. 2 - Typical Output Characteristics

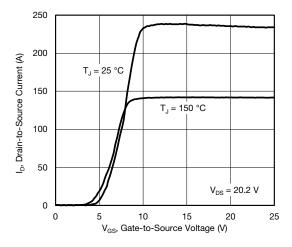


Fig. 3 - Typical Transfer Characteristics

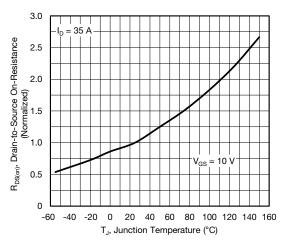


Fig. 4 - Normalized On-Resistance vs. Temperature

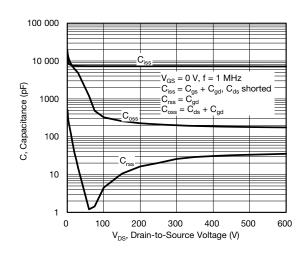


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

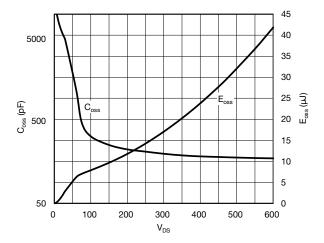


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



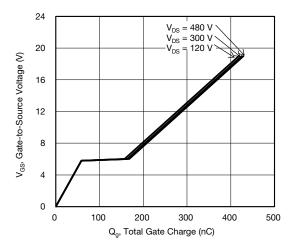


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

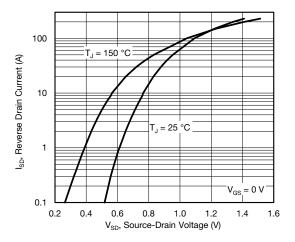


Fig. 8 - Typical Source-Drain Diode Forward Voltage

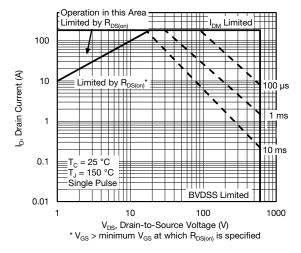


Fig. 9 - Maximum Safe Operating Area

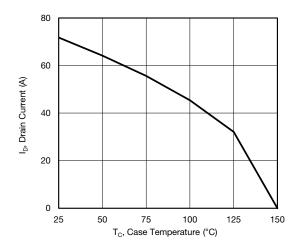


Fig. 10 - Maximum Drain Current vs. Case Temperature

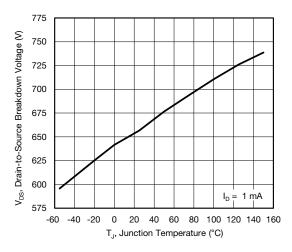


Fig. 11 - Typical Drain-to-Source Voltage vs. Temperature



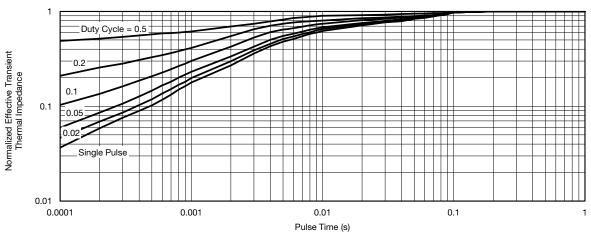
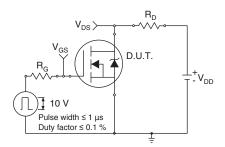


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case



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Fig. 13 - Switching Time Test Circuit

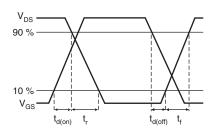


Fig. 14 - Switching Time Waveforms

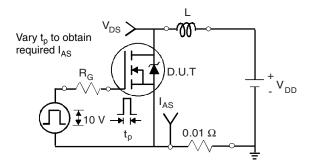


Fig. 15 - Unclamped Inductive Test Circuit

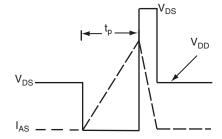


Fig. 16 - Unclamped Inductive Waveforms

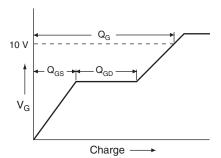


Fig. 17 - Basic Gate Charge Waveform

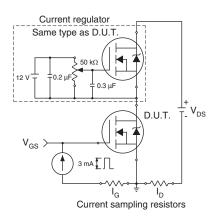
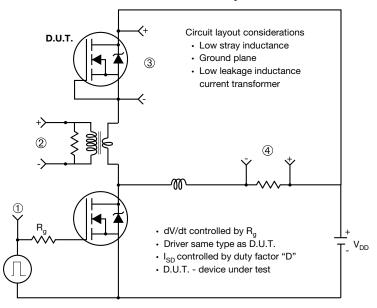


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



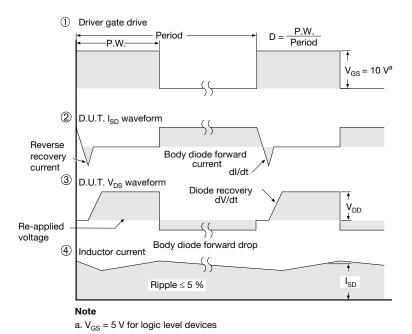
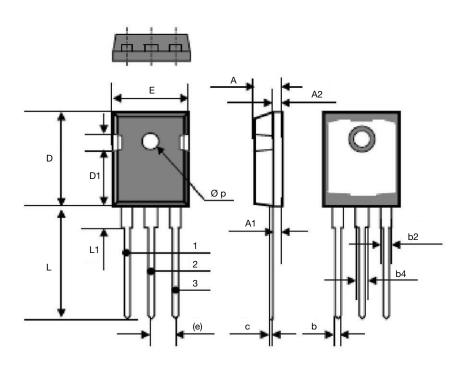


Fig. 19 - For N-Channel

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TO-247AD (High Voltage)



DIM.	MILLIM	IETERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
Α	4.70	5.31	0.185	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.50	2.49	0.059	0.098	
b	0.99	1.40	0.039	0.055	
b2	1.65	2.41	0.065	0.095	
b4	2.59	3.43	0.102	0.135	
С	0.61 BSC		0.024 BSC		
D	20.80	21.46	0.819	0.845	
D1	3.68	5.49	0.145	0.216	
(e)	5.46 BSC		0.215	BSC	
Е	15.49	16.26	0.610	0.640	
L	19.81	20.32	0.780	0.800	
L1	4.06	4.50	0.160	0.177	
Øр	3.51	3.66	0.138	0.144	

ECN: S17-0178-Rev. B, 06-Feb-17

DWG: 6010



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